

## Features

- I<sup>2</sup>C-bus to 16-bit GPIO Expander
- Operating Power Supply Voltage from 1.65 V to 3.6 V
- Low Standby Current Consumption:
  - 1.5 μA (typical at 3.3 V V<sub>CC</sub>)
- 400-kHz Fast-mode I<sup>2</sup>C-bus
- 5-V Tolerant I/Os
- Internal Power-on Reset
- Open-drain Active LOW Interrupt Output ( INT )
- Configurable Slave Address with 2 Address Pins
- Latch-Up Performance exceeds 200 mA per JESD 78
- ESD Protection Exceeds JESD 22
  - ±4000-V Human Body Model
    - ±1500-V Charged Device Model
- AEC Q100: Automotive Grade 1

## Applications

- Automotive ASAS, Infotainment,
- Automotive Body Electronics, EV/HEV
- Servers/Storages/Routers (Telecom Switching Equipment)
- Personal Computers

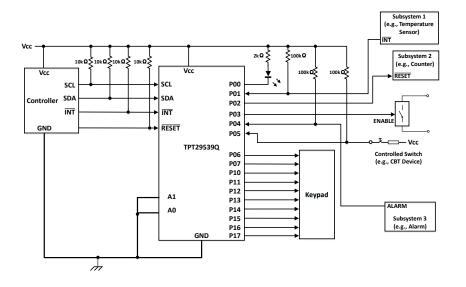
## Description

The TPT29539Q is a 16-bit GPIO expander with interrupt and weak pull-up resistors for  $l^2$ C-bus applications. The power supplier voltage ranges from 1.65 V to 3.6 V, allowing for the TPT29539Q to interconnect with 1.8-V microcontrollers.

The TPT29539Q contains 16-bit Input and Output. The open-drain interrupt ( $\overline{\rm INT}$ ) output is changeable when any input state changes from its related register state. The device is used to indicate the system master that an input state has changed. ( $\overline{\rm INT}$ ) can be connected to the interrupt input of a microcontroller. The TPT29539Q can remain a simple slave device. The power-on reset sets the registers to their default values and initializes the device state machine. The TPT29539Q also has a hardware  $\overline{\rm INT}$  pin to reset the device to its default state.

All input/output pins do not have internal pull-up resistors, thus the device can save power consumption as communicating with external I/Os. Two hardware pins (A0, A1) select the fixed  $I^2$ C-bus address and allow up to eight devices to share the same  $I^2$ C-bus.

The TPT29539Q is available in the TSSOP24 package, and is characterized from  $-40^{\circ}$ C to  $+125^{\circ}$ C to meet automotive application requirements.



# **Typical Application Circuit**



# **Table of Contents**

Applications       1         Description       1         Typical Application Circuit       1         Revision History       3         Pin Configuration and Functions       4         Specifications       6         Absolute Maximum Ratings (1)       6         ESD, Electrostatic Discharge Protection       6         Recommended Operating Conditions       7         Thermal Information       7         Electrical Characteristics       8         Electrical Characteristics (Continued)       9         I <sup>2</sup> C Interface Timing Requirements (1)       10         Switching Characteristics       11         Parameter Measurement Waveforms       11         Typical Performance Characteristics       12         Detailed Description       13         Overview       13         Functional Block Diagram       13         Functional Molementation       17         Application Information       17         Application	Features	1
Typical Application Circuit         1           Revision History         3           Pin Configuration and Functions         4           Specifications         6           Absolute Maximum Ratings (1)         6           ESD, Electrostatic Discharge Protection         6           Recommended Operating Conditions         7           Thermal Information         7           Telectrical Characteristics         8           Electrical Characteristics (Continued)         9           I <sup>2</sup> C Interface Timing Requirements (1)         10           Switching Characteristics         11           Typical Performance Characteristics         12           Detailed Description         13           Overview         13           Functional Block Diagram         13           Functional Block Diagram         14           Device Address         14           Application Information         17           Typical Application         18           Layout Guideline         18           Layout Guideline         18           Layout Example         18           Topolication Information         21           Topolication Information         21           Topolication	Applications	1
Avision History       3         Pin Configuration and Functions       4         Specifications       6         Absolute Maximum Ratings <sup>(1)</sup> 6         ESD, Electrostatic Discharge Protection       6         Recommended Operating Conditions       7         Thermal Information       7         Electrical Characteristics       8         Electrical Characteristics (Continued)       9         I <sup>2</sup> C Interface Timing Requirements <sup>(1)</sup> 10         Switching Characteristics       11         Parameter Measurement Waveforms       11         Typical Performance Characteristics       12         Detailed Description       13         Overview       13         Facture Description       14         Device Address       14         Application and Implementation       17         Application and Implementation       17         Application and Implementation       17         Application and Implementation       17         Typical Application       18         Layout Guideline       18         Layout Guideline       18         Layout Guideline       18         Captare and Reel Information       20	Description	1
Pin Configuration and Functions.       4         Specifications       6         Absolute Maximum Ratings <sup>(1)</sup> 6         ESD, Electrostatic Discharge Protection       6         Recommended Operating Conditions       7         Thermal Information       7         Electrical Characteristics       8         Electrical Characteristics (Continued)       9         I <sup>2</sup> C Interface Timing Requirements <sup>(1)</sup> 10         Switching Characteristics       11         Parameter Measurement Waveforms       11         Typical Performance Characteristics       12         Detailed Description       13         Overview       13         Feature Description       14         Device Address       14         Application Information       17         Application Information       17         rypical Application       18         Layout Guideline       18         Layout Guideline       18         Layout Example       18         Tapout Example       12         Device Address       21         Typical Application       17         Functional Block Diagram       17         Application Information       1	Typical Application Circuit	1
Specifications       6         Absolute Maximum Ratings <sup>(1)</sup> 6         ESD, Electrostatic Discharge Protection       6         Recommended Operating Conditions       7         Thermal Information       7         Electrical Characteristics       8         Electrical Characteristics (Continued)       9         I <sup>2</sup> C Interface Timing Requirements <sup>(1)</sup> 10         Switching Characteristics       11         Parameter Measurement Waveforms       11         Typical Performance Characteristics       12         Detailed Description       13         Overview       13         Feature Description       14         Device Address       14         Application Information       17         Application Information       17         Typical Application       17         Application Information       17         Typical Application       18         Layout Guideline       18         Layout Example       18         Tape and Reel Information       20         Package Outline Dimensions       21         TSSOP24-A       21         Order Information       22 <th>Revision History</th> <th>3</th>	Revision History	3
Absolute Maximum Ratings <sup>(1)</sup>	-	
ESD, Electrostatic Discharge Protection.       6         Recommended Operating Conditions.       7         Thermal Information.       7         Electrical Characteristics.       8         Electrical Characteristics (Continued).       9         I <sup>2</sup> C Interface Timing Requirements <sup>(1)</sup> 10         Switching Characteristics.       11         Parameter Measurement Waveforms.       11         Typical Performance Characteristics.       12         Detailed Description.       13         Overview.       13         Functional Block Diagram.       13         Feature Description.       14         Device Address.       14         Application and Implementation.       17         Application Information       17         Typical Application.       18         Layout Guideline.       18         Layout Example.       18         Tape and Reel Information.       20         Package Outline Dimensions.       21         TSSOP24-A.       21         Order Information.       22	Specifications	6
Recommended Operating Conditions.       7         Thermal Information.       7         Electrical Characteristics       8         Electrical Characteristics (Continued).       9         I <sup>2</sup> C Interface Timing Requirements <sup>(1)</sup> 10         Switching Characteristics       11         Parameter Measurement Waveforms.       11         Typical Performance Characteristics.       12         Detailed Description.       13         Overview.       13         Functional Block Diagram.       13         Feature Description.       14         Device Address.       14         Application Information       17         Typical Application.       17         Application Information       17         Typical Application.       18         Layout Guideline.       18         Layout Example.       18         Cape and Reel Information.       20         Package Outline Dimensions.       21         TSSOP24-A.       21         Order Information.       22	Absolute Maximum Ratings <sup>(1)</sup>	6
Thermal Information       7         Electrical Characteristics       8         Electrical Characteristics (Continued)       9         I <sup>2</sup> C Interface Timing Requirements <sup>(1)</sup> 10         Switching Characteristics       11         Parameter Measurement Waveforms       11         Typical Performance Characteristics       12         Detailed Description       13         Overview       13         Fautre Description       13         Feature Description       14         Device Address       14         Application and Implementation       17         Application Information       17         Typical Application       18         Layout Guideline       18         Layout Example       18         Tape and Reel Information       20         Package Outline Dimensions       21         TSSOP24-A       21         Order Information       22	ESD, Electrostatic Discharge Protection	6
Electrical Characteristics       8         Electrical Characteristics (Continued).       9         I <sup>2</sup> C Interface Timing Requirements <sup>(1)</sup> 10         Switching Characteristics       11         Parameter Measurement Waveforms       11         Typical Performance Characteristics       12         Detailed Description       13         Overview       13         Functional Block Diagram       13         Feature Description       14         Device Address       14         Application and Implementation       17         Application Information       17         Typical Application       18         Layout Guideline       18         Layout Example       18         Sage Outline Dimensions       21         TSSOP24-A       21         Order Information       22	Recommended Operating Conditions	7
Electrical Characteristics (Continued).       9         I <sup>2</sup> C Interface Timing Requirements <sup>(1)</sup> 10         Switching Characteristics.       11         Parameter Measurement Waveforms.       11         Typical Performance Characteristics.       12         Detailed Description.       13         Overview.       13         Functional Block Diagram.       13         Feature Description.       14         Device Address.       14         Application and Implementation.       17         Application Information       17         Typical Application.       18         Layout Guideline.       18         Layout Example.       18         Tape and Reel Information.       20         Package Outline Dimensions.       21         TSSOP24-A.       21	Thermal Information	7
I <sup>2</sup> C Interface Timing Requirements <sup>(1)</sup> 10         Switching Characteristics       11         Parameter Measurement Waveforms       11         Typical Performance Characteristics       12         Detailed Description       13         Overview       13         Functional Block Diagram       13         Feature Description       14         Device Address       14         Application and Implementation       17         Application Information       17         Typical Application       18         Layout Guideline       18         Layout Example       18         TSSOP24-A       21         Order Information       22	Electrical Characteristics	8
Switching Characteristics       11         Parameter Measurement Waveforms       11         Typical Performance Characteristics       12         Detailed Description       13         Overview       13         Functional Block Diagram       13         Feature Description       14         Device Address       14         Application and Implementation       17         Application Information       17         Typical Application       18         Layout Guideline       18         Layout Example       18         Tase and Reel Information       20         Package Outline Dimensions       21         TSSOP24-A       21         Drder Information       22	Electrical Characteristics (Continued)	9
Parameter Measurement Waveforms       11         Typical Performance Characteristics       12         Detailed Description       13         Overview       13         Functional Block Diagram       13         Feature Description       14         Device Address       14         Application and Implementation       17         Application Information       17         Typical Application       17         Application Information       17         Typical Application       17         Application Information       17         Typical Application       17         Tayout       18         Layout Guideline       18         Layout Example       18         Tape and Reel Information       20         Package Outline Dimensions       21         TSSOP24-A       21         Order Information       22	I <sup>2</sup> C Interface Timing Requirements <sup>(1)</sup>	10
Typical Performance Characteristics.       12         Detailed Description.       13         Overview.       13         Functional Block Diagram.       13         Feature Description.       14         Device Address.       14         Application and Implementation.       17         Application Information       17         Typical Application.       17         Application Information       17         Typical Application.       18         Layout Guideline.       18         Layout Example.       18         Tape and Reel Information.       20         Package Outline Dimensions.       21         TSSOP24-A.       21         Order Information.       22	Switching Characteristics	11
Detailed Description       13         Overview       13         Functional Block Diagram       13         Feature Description       14         Device Address       14         Application and Implementation       17         Application Information       17         Typical Application       17         ayout       18         Layout Guideline       18         Tape and Reel Information       20         Package Outline Dimensions       21         Order Information       21         Order Information       22	Parameter Measurement Waveforms	11
Overview.       13         Functional Block Diagram.       13         Feature Description.       14         Device Address.       14         Application and Implementation.       17         Application Information       17         Typical Application.       17         ayout.       18         Layout Guideline.       18         Layout Example.       18         Tape and Reel Information.       20         Package Outline Dimensions.       21         Drder Information.       21         Order Information.       22	Typical Performance Characteristics	12
Functional Block Diagram       13         Feature Description       14         Device Address       14         Application and Implementation       17         Application Information       17         Typical Application       17         ayout       18         Layout Guideline       18         Layout Example       18         Fape and Reel Information       20         Package Outline Dimensions       21         Drder Information       21         Order Information       21	Detailed Description	13
Feature Description       14         Device Address       14         Application and Implementation       17         Application Information       17         Typical Application       17         .ayout       18         Layout Guideline       18         Layout Example       18         Fape and Reel Information       20         Package Outline Dimensions       21         TSSOP24-A       21         Order Information       22	Overview	13
Device Address       14         Application and Implementation       17         Application Information       17         Typical Application       17         .ayout       18         Layout Guideline       18         Layout Example       18         Tape and Reel Information       20         Package Outline Dimensions       21         TSSOP24-A       21         Order Information       22	Functional Block Diagram	13
Application and Implementation.17Application Information17Typical Application.17.ayout.18Layout Guideline.18Layout Example.18Fape and Reel Information.20Package Outline Dimensions.21TSSOP24-A.21Order Information.22	Feature Description	14
Application Information 17   Typical Application 17   ayout 18   Layout Guideline 18   Layout Example 18   Tape and Reel Information 20   Package Outline Dimensions 21   TSSOP24-A 21   Order Information 22	Device Address	14
Typical Application       17         .ayout       18         Layout Guideline       18         Layout Example       18         Fape and Reel Information       20         Package Outline Dimensions       21         TSSOP24-A       21         Order Information       22	Application and Implementation	17
Layout       18         Layout Guideline       18         Layout Example       18         Fape and Reel Information       20         Package Outline Dimensions       21         TSSOP24-A       21         Order Information       22	Application Information	17
Layout Guideline.       18         Layout Example.       18         Tape and Reel Information.       20         Package Outline Dimensions.       21         TSSOP24-A.       21         Order Information.       22	Typical Application	17
Layout Example	Layout	18
Fape and Reel Information	Layout Guideline	18
Package Outline Dimensions	Layout Example	
TSSOP24-A	Tape and Reel Information	20
Order Information	Package Outline Dimensions	21
	TSSOP24-A	21
MPORTANT NOTICE AND DISCLAIMER	Order Information	22
	IMPORTANT NOTICE AND DISCLAIMER	23



# **Revision History**

Date	Revision	Notes
2023-12-18	Rev.A.0	Released version
2024-02-07	Rev.A.1	Updated Typical Application Circuit
2024-02-20	Rev.A.2	Updated the V <sub>OH</sub> /I <sub>OL</sub> /I <sub>CC</sub> test condition
2024-03-31	Rev.A.3	Updated the standby $I_{CC}$ as input low condition
2024-06-26	Rev.A.4	Added the Reset timing and updated the tps spec
2024-08-12	Rev.A.5	Corrected the typo of the K0 value of 1.6 to 1.25 in the Tape and Reel Information section



# **Pin Configuration and Functions**

	TSSOP24 Packag Top View	je	
	$^{1}$	24	
A1	2	23	SDA SDA
	3	22	
P0_0	4	21	A0
P0_1	5	20	P1_7
P0_2	6	19	P1_6
P0_3	7	18	P1_5
P0_4	8	17	P1_4
P0_5	9	16	P1_3
P0_6	10	15	P1_2
P0_7	11	14	P1_1
	12	13	P1_0
0.10		10	

TPT29539Q

#### Table 1. Pin Functions: TPT29539Q

Pin No.	Name	I/O	Description
21	A0	Input	Address input 0. Connect directly to VCC or ground
2	A1	Input	Address input 1. Connect directly to VCC or ground
3	RESET	Input	RESET input, active LOW
12	GND	GND	Ground
1	ĪNT	Output	Interrupt output. Connect to VCC through a pull-up resistor
4	P0_0	I/O	P-port I/O. Push-pull design structure. At power on, P0_0 is configured as an input
5	P0_1	I/O	P-port I/O. Push-pull design structure. At power on, P0_1 is configured as an input
6	P0_2	I/O	P-port I/O. Push-pull design structure. At power on, P0_2 is configured as an input
7	P0_3	I/O	P-port I/O. Push-pull design structure. At power on, P0_3 is configured as an input
8	P0_4	I/O	P-port I/O. Push-pull design structure. At power on, P0_4 is configured as an input
9	P0_5	I/O	P-port I/O. Push-pull design structure. At power on, P0_5 is configured as an input
10	P0_6	I/O	P-port I/O. Push-pull design structure. At power on, P0_6 is configured as an input
11	P0_7	I/O	P-port I/O. Push-pull design structure. At power on, P0_7 is configured as an input
13	P1_0	I/O	P-port I/O. Push-pull design structure. At power on, P1_0 is configured as an input
14	P1_1	I/O	P-port I/O. Push-pull design structure. At power on, P1_1 is configured as an input
15	P1_2	I/O	P-port I/O. Push-pull design structure. At power on, P1_2 is configured as an input
16	P1_3	I/O	P-port I/O. Push-pull design structure. At power on, P1_3 is configured as an input
17	P1_4	I/O	P-port I/O. Push-pull design structure. At power on, P1_4 is configured as an input
18	P1_5	I/O	P-port I/O. Push-pull design structure. At power on, P1_5 is configured as an input
19	P1_6	I/O	P-port I/O. Push-pull design structure. At power on, P1_6 is configured as an input
20	P1_7	I/O	P-port I/O. Push-pull design structure. At power on, P1_7 is configured as an input



Pin No.	Name	I/O	Description
22	SCL	Input	Serial clock bus. Connect to VCC through a pull-up resistor
23	SDA	I/O	Serial data bus. Connect to VCC through a pull-up resistor
24	VCC	Supply	Supply voltage



# **Specifications**

### Absolute Maximum Ratings <sup>(1)</sup>

	Parameter	Min	Max	Unit
Vcc	Supply Voltage	-0.5	3.6	V
VI	Input Voltage	-0.5	3.6	V
Vo	Output Voltage	-0.5	3.6	V
I <sub>IK</sub>	Input Clamp Current, VI < 0		-20	mA
loк	Output Clamp Current, V <sub>O</sub> < 0		-20	mA
I <sub>IOK</sub>	Input-Output Clamp Current, $V_0 < 0$ or $V_0 > V_{CC}$		±20	mA
I <sub>OL</sub>	Continuous Output Low Current, Vo = 0 to Vcc		50	mA
I <sub>OH</sub>	Continuous Output High Current, $V_0 = 0$ to $V_{CC}$		-50	mA
	Continuous Current through GND		-250	mA
Icc	Continuous Current through V <sub>CC</sub>		160	mA
TJ	Maximum Junction Temperature		135	°C
T <sub>stg</sub>	Storage Temperature	-65	150	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

(2) This data was taken with the JEDEC low effective thermal conductivity test board.

(3) This data was taken with the JEDEC standard multilayer test boards.

### ESD, Electrostatic Discharge Protection

	Parameter	Condition	Minimum Level	Unit
НВМ	Human Body Model ESD	ANSI/ESDA/JEDEC JS-001 (1)	±4	kV
CDM	Charged Device Model ESD	ANSI/ESDA/JEDEC JS-002 <sup>(2)</sup>	±1.5	kV

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.



### **Recommended Operating Conditions**

Over-operating free-air temperature range (unless otherwise noted).

	Par	rameter	Min	Max	Unit
Vcc	Supply Voltage		1.65	3.6	V
	Output IO Voltage	P0_7 ~ P0_0, P1_7 ~ P1_0	0	3.6	V
VIO	Input IO Voltage	P0_7 ~ P0_0, P1_7 ~ P1_0	0	3.6	V
	IO Voltage	SCL, SDA, A1, A0, RESET, INT	0	3.6	V
VIH		SCL, SDA	0.7 × V <sub>CC</sub>	V <sub>cc</sub>	V
	High-Level Input Voltage	RESET, A2 ~ A0, P0_7 ~ P0_0, P1_7 ~ P1_0	0.7 × Vcc	Vcc	V
		SCL, SDA	-0.5	0.3 × V <sub>CC</sub>	mV
VIL	Low-Level Input Voltage	RESET, A2 ~ A0, P0_7 ~ P0_0, P1_7 ~ P1_0	-0.5	0.3 × V <sub>CC</sub>	mV
Іон	High-Level Output Current	P0_7 ~ P0_0, P1_7 ~ P1_0		-10	mA
		P0_7 ~ P0_0, P1_7 ~ P1_0		25	mA
I <sub>OL</sub>	Low-Level Output Current	ĪNT, SDA		6	mA
TA	T <sub>A</sub> Operating Temperature Range		-40	125	°C

### Thermal Information

Package Type	θ <sub>JA</sub>	θ」ϲ	Unit
TSSOP24	68	21	°C/W



### **Electrical Characteristics**

All test conditions:  $V_{CC}$  = 1.65 V ~ 3.6 V,  $T_A$  = -40 ~ +125°C, unless otherwise noted.

	Parameter	Conditions	Min	Тур	Max	Unit
Input El	ectrical Specifications					
.,	Power-on Reset Voltage , $V_{\text{CC}}$ rising	$V_I = V_{CC}$ or GND; $I_0 = 0$ mA		1.25	1.5	V
Vpor	Power-on Reset Voltage , $V_{CC}$ falling	VI = Vcc or GND; Io = 0 mA	0.7	1.2		V
	LOW-level Output Current, SDA	$V_{OL}$ = 0.4 V; $V_{CC}$ = 1.65 V to 3.6 V	3			mA
	LOW-level Output Current, INT	$V_{OL}$ = 0.4 V; $V_{CC}$ = 1.65 V to 3.6 V	3			mA
		V <sub>OL</sub> = 0.5 V; V <sub>CC</sub> = 1.65 V	8			mA
	LOW-level Output Current, P port	$V_{OL}$ = 0.5 V; $V_{CC}$ = 2.3 V <sup>(1)</sup>	8			mA
IOL		V <sub>OL</sub> = 0.5 V; V <sub>CC</sub> = 3.0 V	8			mA
	LOW-level Output Current, P port	V <sub>OL</sub> = 0.7 V; V <sub>CC</sub> = 1.65 V	10			mA
		$V_{OL}$ = 0.7 V; $V_{CC}$ = 2.3 V <sup>(1)</sup>	10			mA
		V <sub>OL</sub> = 0.7 V; V <sub>CC</sub> = 3.0 V	10			mA
		Iон= −8 mA; V <sub>CC</sub> = 1.65 V	1.2			V
	HIGH-level Output Voltage, P port	$I_{OH}$ = -8 mA; $V_{CC}$ = 2.3 V <sup>(1)</sup>	1.8			V
	port	I <sub>OH</sub> = -8 mA; V <sub>CC</sub> = 3.0 V	2.6			V
V <sub>он</sub>		Iон= −10 mA; Vcc= 1.65 V	1.0			V
	HIGH-level Output Voltage, P port	$I_{OH} = -10 \text{ mA}; V_{CC} = 2.3 \text{ V}^{(1)}$	1.7			V
	port	I <sub>OH</sub> = −10 mA; V <sub>CC</sub> = 3.0 V	2.5			V
	Input Current: A0, A1, RESET	V <sub>CC</sub> = 1.65 V to 3.6 V, V <sub>I</sub> = V <sub>CC</sub> or GND	-1		1	μA
lı	Input Current: SCL, SDA	$V_{CC}$ = 1.65 V to 3.6 V, $V_{I}$ = $V_{CC}$ or GND	-1		1	μA
IIH	HIGH-level Input Current: P port	$V_{I}$ = $V_{CC}$ ; $V_{CC}$ = 1.65 V to 3.6 V			1	μA
l <sub>IL</sub>	LOW-level Input Current: P Port	V <sub>I</sub> = GND; V <sub>CC</sub> = 1.65 V to 3.6 V	-1			μA

(1) Parameters are provided by lab bench tests and design simulation. Not tested in production.



### **Electrical Characteristics (Continued)**

All test conditions:  $V_{CC}$  = 1.65 V ~ 3.6 V,  $T_A$  = -40 ~ +125°C, unless otherwise noted.

	Parameter	Conditions		Min	Тур	Max	Unit
			V <sub>CC</sub> = 3.6 V		9	30	μA
		Active mode, IO = 0 mA; I/O = inputs; fSCL = 400 kHz	V <sub>CC</sub> = 2.7 V <sup>(1)</sup>		6.2	19	μA
			Vcc= 1.95 V		4.2	11	μA
		Standby Mode, input low, IO	V <sub>CC</sub> = 3.6 V		3.0	5.0	μA
Icc	Supply Current	= 0 mA; I/O = inputs; $fS_{SCL}$ =	V <sub>CC</sub> = 2.7 V <sup>(1)</sup>		2.0	4.5	μA
		0 kHz	Vcc= 1.95 V		1.5	3.5	μA
		Standby Mode, input high, IO = 0 mA; I/O = inputs; f <sub>SCL</sub> = 0 kHz	V <sub>CC</sub> = 3.6 V		1.5	5.0	μA
			$V_{CC}$ = 2.7 V <sup>(1)</sup>		1.0	4.5	μA
			Vcc= 1.95 V		0.6	3.5	μA
C <sub>i</sub> <sup>(1)</sup>	Input Capacitance	$V_{\text{I}}\text{=}V_{\text{CC}}$ or GND; $V_{\text{CC}}\text{=}$ 1.65 V to 3.6 V $^{(1)}$			3		pF
C <sub>io</sub> <sup>(1)</sup>		$V_{\text{I/O}}\text{=}$ $V_{\text{CC}}$ or GND; $V_{\text{D}}\text{=}$ 1.65 V to 3.6 V $^{(1)}$			3		pF
	Input/Output Capacitance	V <sub>I/O</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 1.65 V to 3.6 V <sup>(1)</sup>			5		pF

(1) Parameters are provided by lab bench tests and design simulation. Not tested in production.



### I<sup>2</sup>C Interface Timing Requirements <sup>(1)</sup>

Over recommended operating free-air temperature range, unless otherwise noted.

<b>-</b> <i></i>			Standa	Standard Mod		Fast Mode	
	Description	Conditions	Min	Max	Min	Max	Unit
fscl	I <sup>2</sup> C clock frequency		0	100	0	400	kHz
tsch	I <sup>2</sup> C clock high time		4		0.6		μs
tscl	I <sup>2</sup> C clock low time		4.7		1.3		μs
tsp	I <sup>2</sup> C spike time			50		50	ns
tsds	I <sup>2</sup> C serial-data setup time		250		100		ns
tsdh	I <sup>2</sup> C serial-data hold time		0		0		ns
ticr <sup>(2)</sup>	I <sup>2</sup> C input rise time			1000	20	300	ns
ticf <sup>(3)</sup>	I <sup>2</sup> C input fall time			300	20 × (Vcc/ 3.6 V)	300	ns
tocf <sup>(3)</sup>	I <sup>2</sup> C output fall time	10-pF to 400-pF bus		300	20 × (V <sub>cc</sub> / 3.6 V)	300	ns
tbuf	I <sup>2</sup> C bus free time between stop and start		4.7		1.3		μs
tsts	I <sup>2</sup> C start or repeated start condition setup		4.7		0.6		μs
tsth	I <sup>2</sup> C start or repeated start condition hold		4		0.6		μs
tsps	I <sup>2</sup> C stop condition setup		4		0.6		μs
tvd(data)	Valid data time	SCL low to SDA output valid		3.5		0.9	μs
tvd(ack)	Valid data time of ACK condition	ACK signal from SCL low to SDA (out) low		3.5		0.9	μs
Cb	I <sup>2</sup> C bus capacitive load			400		400	pF

(1) All timing requirements should refer to I<sup>2</sup>C standard, and all parameters in table are NOT tested in production.

(2) ticr is decided by input signal rising time.

(3) Data is provided by bench validation, test condition: 150ohm series resistor connect to SDA pin, then 2.2 Kohm pull up to VCC, 150 pF Cload pull down to GND, t<sub>icr</sub> = 29 ns, t<sub>ocf</sub> = 25 ns, V<sub>OL</sub> = 166 mv.



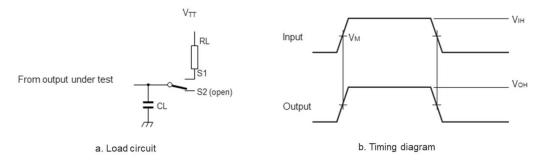
### **Switching Characteristics**

Over recommended operating free-air temperature range,  $C_L \leq 100 \text{ pF}$ , unless otherwise noted.

	Description	From	То	Standa	ard Mod	Fast Mode		11
	Description	(Input)	(Output)	Min	Max	Min	Max	Unit
tiv	Interrupt valid time	P port	ĪNT		4		4	μs
tir	Interrupt reset delay time	SCL	ĪNT		4		4	μs
4	Output data valid; For V <sub>CC</sub> = 2.3 V $\sim$ 3.6 V		Durant		400		400	ns
	Output data valid; For V_{CC} = 1.65 V $\sim 2.3 \ V$	SCL	P port		400		400	ns
tps	Input data setup time	P port	SCL	150		150		ns
tph	Input data hold time	P port	SCL	1		1		μs

Parameter	,	Condition	min	typ	max	Unit
RESET Timing Requirements						
tW	Reset pules duration		60			ns
tREC	Reset recovery time		0		15	ns
4DEOET	Time to reset	For VCC = 2.3 V~3.6 V	400			
tRESET	Time to reset	For VCC = 1.65 V – 2.3 V	550			ns

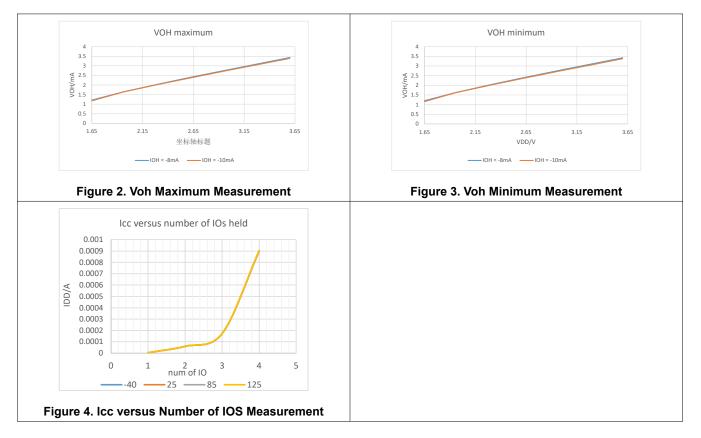
### **Parameter Measurement Waveforms**







### **Typical Performance Characteristics**





## **Detailed Description**

### Overview

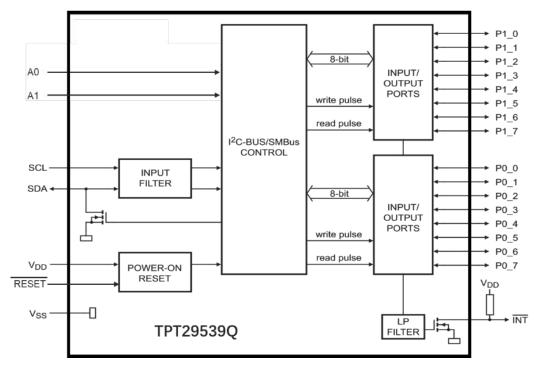
The TPT29539Q is a 16-bit GPIO expander with interrupt and weak pull-up resistors for I<sup>2</sup>C-bus applications. The power supplier voltage ranges from 1.65 V to 3.6 V, allowing for the TPT29539Q to interconnect with 1.8-V microcontrollers.

The TPT29539Q contains 16-bit Input and Output. The open-drain interrupt ( $\overline{INT}$ ) output is changeable when any input state changes from its related register state. The device is used to indicate the system master that an input state has changed. ( $\overline{INT}$ ) can be connected to the interrupt input of a microcontroller. The TPT29539Q can remain a simple slave device. The power-on reset sets the registers to their default values and initializes the device state machine. The TPT29539Q also has a hardware  $\overline{INT}$  pin to reset the device to its default state.

All input/output pins do not have internal pull-up resistors, thus the device can save power consumption as communicating with external I/Os. Two hardware pins (A0, A1) select the fixed  $I^2$ C-bus address and allow up to eight devices to share the same  $I^2$ C-bus.

The TPT29539Q is available in the TSSOP24 package, and is characterized from -40°C to +125°C to meet automotive application requirements.

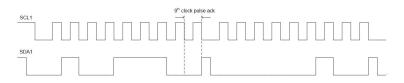




#### Figure 5. Functional Block Diagram



### **Feature Description**



#### Figure 6. I<sup>2</sup>C BUS (1.65 V ~ 3.6 V) Waveform

#### **Device Address**

Following a START condition, the bus master must output the address of the slave it is accessing. All input/output pins have internal weak pull-up resistors to remove external components. Two hardware pins (A0, A1) select the fixed  $l^2$ C-bus address and allow up to eight devices to share the same  $l^2$ C-bus. To conserve power, address pins (A0, A1) must be pulled HIGH or LOW. The address of the TPT29539Q is shown below.

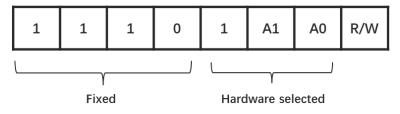


Figure 7. Slave Device Address

#### **Control Register**

#### **Command Byte**

The command byte is the first byte to follow the address byte during a write transmission. It is used as a pointer to determine which of the following registers will be written or read.

Table 2. Command	Byte Description
------------------	------------------

Command	Register
0	Input port 0
1	Input port 1
2	Output port 0
3	Output port 1
4	Polarity Inversion port 0
5	Polarity Inversion port 1
6	Configuration port 0
7	Configuration port 1

#### Register 0 and 1: Input port registers

This register is an input-only port, which means the incoming logic levels of the pins, regardless of whether the pin is defined as an input or an output by Register 3 ( output port 1 ) ,and writes to this register have no effect.

The default value 'X' is determined by the externally logic level.



Bit	7	6	5	4	3	2	1	0
Symbol	10.7	10.6	10.5	10.4	10.3	10.2	10.1	10.0
Default	Х	Х	Х	Х	Х	Х	Х	Х

#### Table 4. Input Port 1 Register

Bit	7	6	5	4	3	2	1	0
Symbol	l1.7	I1.6	l1.5	l1.4	l1.3	l1.2	l1.1	l1.0
Default	Х	Х	Х	Х	Х	Х	Х	Х

#### Register 2 and 3: Output port registers

This register is an output-only port, which means the outcoming logic levels of the pins are defined as outputs by Register 6 (Configuration port 0) and 7 (Configuration port 1). Bit values in this register have no effect on pins defined as inputs. In fact, the value reading from this register is in the flip-flop controlling the output selection, not the actual pin value.

#### Table 5. Output Port 0 Register

Bit	7	6	5	4	3	2	1	0
Symbol	O0.7	O0.6	O0.5	O0.4	O0.3	O0.2	O0.1	O0.0
Default	1	1	1	1	1	1	1	1

#### Table 6. Output Port 1 Register

Bit	7	6	5	4	3	2	1	0
Symbol	01.7	O1.6	O1.5	01.4	01.3	01.2	O1.1	O1.0
Default	1	1	1	1	1	1	1	1

#### **Register 4 and 5: Polarity Inversion registers**

This register allows the user to invert the polarity of the input port register data. If a bit in this register is set (written with '1'), the input port data polarity is inverted. If a bit in this register is cleared (written with '0'), the input port data polarity is retained.

#### Table 7. Polarity Inversion Port 0 Register

Bit	7	6	5	4	3	2	1	0
Symbol	N0.7	N0.6	N0.5	N0.4	N0.3	N0.2	N0.1	N0.0
Default	0	0	0	0	0	0	0	0

#### Table 8. Polarity Inversion Port 1 Register

Bit	7	6	5	4	3	2	1	0
Symbol	N1.7	N1.6	N1.5	N1.4	N1.3	N1.2	N1.1	N1.0
Default	0	0	0	0	0	0	0	0



#### **Register 6 and 7: Configuration registers**

This register configures the directions of the I/O pins. If a bit in this register is set (written with '1'), the corresponding port pin is enabled as an input with a high-impedance output driver. If a bit in this register is cleared (written with '0'), the corresponding port pin is enabled as an output. Note that there is a high-value resistor tied to  $V_{DD}$  at each pin. At reset, the device's ports are inputs with a pull-up to  $V_{DD}$ .

Bit	7	6	5	4	3	2	1	0
Symbol	C0.7	C0.6	C0.5	C0.4	C0.3	C0.2	C0.1	C0.0
Default	1	1	1	1	1	1	1	1

#### Table 9. Configuration port 0 Register

#### Table 10. Configuration port 1 Register

Bit	7	6	5	4	3	2	1	0
Symbol	C1.7	C1.6	C1.5	C1.4	C1.3	C1.2	C1.1	C1.0
Default	1	1	1	1	1	1	1	1



## **Application and Implementation**

Note

Information in the following application sections is not part of the 3PEAK's component specification and 3PEAK does not warrant its accuracy or completeness. 3PEAK's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### **Application Information**

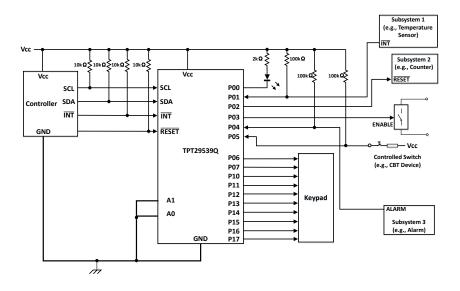
The TPT29539Q builds in 16-bit input and output, and interrupt  $\overline{\text{INT}}$  can be connected to the interrupt input of a microcontroller, then the interrupt  $\overline{\text{INT}}$  output will response to any input state change.

#### **IO Configuration Requirements**

To make sure the TPT29539Q can support the different application, the device is requested to set all GPIOs a default value after or before powering up the device. Or the backup method, after powering up the TPT29539Q, registers are reset to a default value by digital circuit while GPIOs status are not yet stable, because there is no pull-up/pull-down resistors inside. The digital circuit is monitoring and comparing the GPIOs status to the default value of the registers in real time and when they are not matched, during the unstable period, the INT is locked. This has been confirmed in lab testing by adding time delay in seconds after powering up the TPT29539Q (for GPIOs status to reach a stable status). After seconds, the INT function is ready to work, and the performance is exactly as designed. The delay time will depend on the different capacitance on board.

### **Typical Application**

One application of the TPT29539Q device is used as below.







### Layout

### Layout Guideline

Reflections and matching are closely related to loop antenna theory, but different enough to warrant their own discussion. When a PCB trace turns a corner at a 90° angle, a reflection can occur. This is primarily due to the change in the width of the trace. At the apex of the turn, the trace width is increased to 1.414 times its width. This change in width upsets the transmission line characteristics, especially the distributed capacitance and self-inductance of the trace, thus resulting in the reflection. Not all PCB traces can be straight, so they will have to turn corners. Figure 9 shows progressively better techniques of rounding corners. Only the last example (BEST) maintains constant trace width and minimizes reflections.

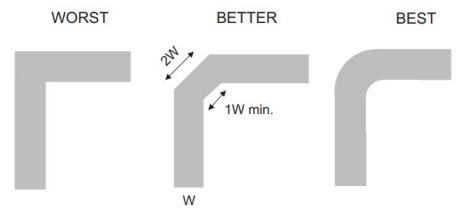


Figure 9. Trace Example

Route high-speed signals using a minimum of vias and corners which reduces signal reflections and impedance changes. When a via must be used, increase the clearance size around it to minimize its capacitance. Each via introduces discontinuities in the signal's transmission line and increases the chance of picking up interference from the other layers of the board. Be careful when designing test points, through-hole pins are not recommended at high frequencies.

### Layout Example

Figure 10 illustrates an example of a PCB layout with the TPT29539Q. Some key considerations are as follows:

- Decouple the VDD pin with a 0.1-µF capacitor, placed it as close to the pin as possible. Make sure that the capacitor voltage rating is sufficient for the VDD supply.
- Keep the input lines as short as possible.
- Use a solid ground plane to help reduce electromagnetic interference (EMI) noise pickup.
- Do not run sensitive analog traces in parallel with digital traces. Avoid crossing digital and analog traces if possible, and only make perpendicular crossings when necessary.



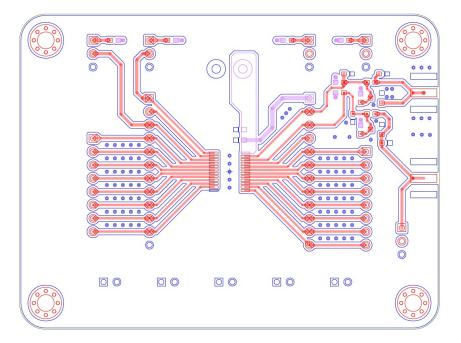
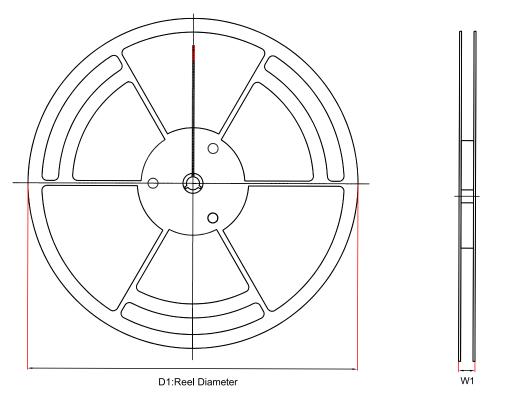
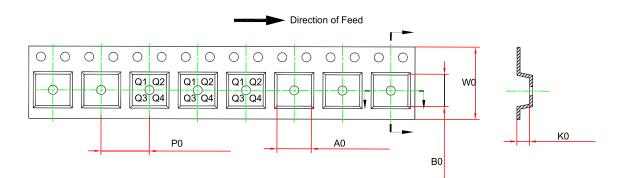


Figure 10. TPT29539Q Layout Example



# Tape and Reel Information



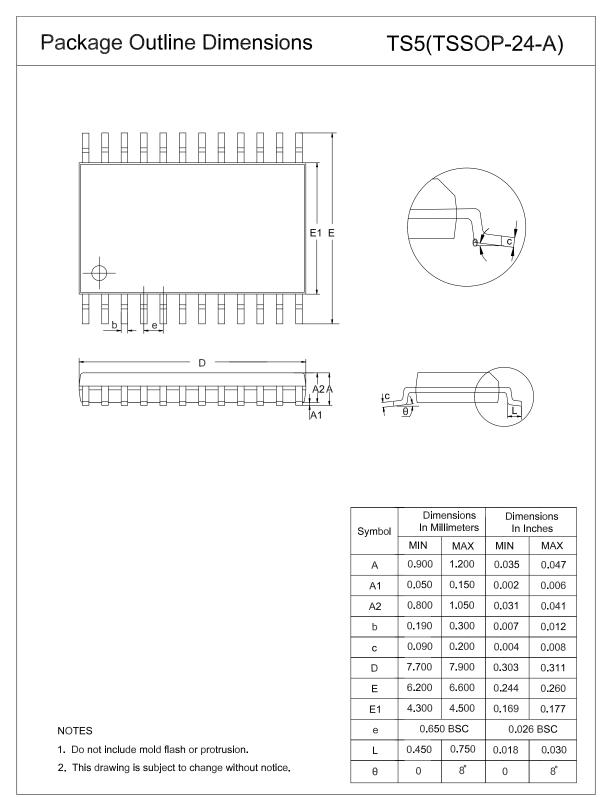


Order Number	Package	D1 (mm)	W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	W0 (mm)	Pin1 Quadrant
TPT29539Q- TS5R-S	TSSOP24	330	21.6	6.8	8.3	1.25	8	16	Q1



## **Package Outline Dimensions**

### TSSOP24-A





### **Order Information**

Order Number	Operating Temperature Range	Package	Marking Information	MSL	Transport Media, Quantity	Eco Plan
TPT29539Q-TS5R-S	−40 to 125°C	TSSOP24	9539Q	MSL3	4,000	Green

**Green**: 3PEAK defines "Green" to mean RoHS compatible and free of halogen substances.



## IMPORTANT NOTICE AND DISCLAIMER

Copyright<sup>©</sup> 3PEAK 2012-2024. All rights reserved.

**Trademarks.** Any of the 思瑞浦 or 3PEAK trade names, trademarks, graphic marks, and domain names contained in this document /material are the property of 3PEAK. You may NOT reproduce, modify, publish, transmit or distribute any Trademark without the prior written consent of 3PEAK.

**Performance Information.** Performance tests or performance range contained in this document/material are either results of design simulation or actual tests conducted under designated testing environment. Any variation in testing environment or simulation environment, including but not limited to testing method, testing process or testing temperature, may affect actual performance of the product.

**Disclaimer.** 3PEAK provides technical and reliability data (including data sheets), design resources (including reference designs), application or other design recommendations, networking tools, security information and other resources "As Is". 3PEAK makes no warranty as to the absence of defects, and makes no warranties of any kind, express or implied, including without limitation, implied warranties as to merchantability, fitness for a particular purpose or non-infringement of any third-party's intellectual property rights. Unless otherwise specified in writing, products supplied by 3PEAK are not designed to be used in any life-threatening scenarios, including critical medical applications, automotive safety-critical systems, aviation, aerospace, or any situations where failure could result in bodily harm, loss of life, or significant property damage. 3PEAK disclaims all liability for any such unauthorized use.



## **TPT29539Q**

Automotive I<sup>2</sup>C to 16-bit GPIO Expander with Interrupt and Reset

This page intentionally left blank